

What is claimed is:

1. A high dielectric resin composition comprising:
a high dielectric filler; and
resin;

wherein a relative dielectric constant of the high dielectric filler satisfies the following formulae (1) and (2),

$$[(\epsilon_T - \epsilon_{25}) / \epsilon_{25}]_{\text{MAX}} \leq 0.03 \quad (1)$$

$$40 \leq \epsilon_{25} \leq 1000 \quad (2)$$

wherein, ϵ_T represents the relative dielectric constant of the high dielectric filler at a temperature T, the temperature T is from to -20 to 80°C, ϵ_{25} represents the relative dielectric constant of the high dielectric filler at a temperature of 25°C, and $[(\epsilon_T - \epsilon_{25}) / \epsilon_{25}]_{\text{MAX}}$ denotes a maximum value of an absolute value of a relative dielectric constant variation $(\epsilon_T - \epsilon_{25}) / \epsilon_{25}$.

2. The composition according to Claim 1, wherein the composition further comprises a solvent.

3. The composition according to any one of Claims 1 or 2, wherein the resin is aromatic liquid-crystalline polyester.

4. The composition according to Claim 3, wherein the aromatic liquid-crystalline polyester comprises 30 to 80 mol% of a repeating unit derived from at least one compound selected from the group consisting of p-hydroxybenzoic acid and 2-hydroxy-6-naphthoic acid, 10 to 35 mol% of a repeating unit derived from at least one compound selected from the group consisting of hydroquinone and 4,4'-dihydroxybiphenyl, and 10

to 35 mol% of a repeating unit derived from at least one compound selected from the group consisting of terephthalic acid, isophthalic acid and 2,6-naphthalenediol.

5. The composition according to Claim 2, wherein the solvent contains a halogen-substituted phenolic compound.

6. The composition according to Claim 5, wherein a content of the halogen-substituted phenolic compound is 30 weight % or more of the solvent.

7. The composition according to Claim 1, wherein the resin is aromatic polysulfone.

8. The composition according to Claim 1, wherein the resin is aromatic polyether sulfone.

9. The composition according to Claim 2, wherein the resin is aromatic polysulfone.

10. The composition according to Claim 2, wherein the resin is aromatic polyether sulfone.

11. The composition according to any one of Claims 9 or 10, wherein the solvent contains methylene chloride.

12. The composition according to Claim 11, wherein the amount of methylene chloride is not less than 80 weight % of the solvent.

13. The composition according to Claim 1, wherein the high dielectric filler is at least one selected from the group consisting of Al_2O_3 , BN, BaO, BeO, Bi_2O_3 , CaO, Cr_2O_3 , Fe_2O_3 , La_2O_3 , Na_2O , Nd_2O_3 , SiC, Si_2N_4 , SiO_2 , SrO, TiO_2 , Y_2O_3 , ZrO_2 .

14. The composition according to Claim 13, wherein the high dielectric filler is at least two selected from the group consisting of BaO, Bi₂O₃, La₂O₃, Nd₂O₃ and TiO₂.

15. The composition according to Claim 14, wherein the high dielectric filler is TiO₂ and at least one selected from the group consisting of BaO, Bi₂O₃, La₂O₃ and Nd₂O₃.

16. A high dielectric resin film comprising a high dielectric filler; and

resin;

wherein a relative dielectric constant of the high dielectric filler satisfies the following formulae (1) and (2),

$$[(\epsilon_T - \epsilon_{25}) / \epsilon_{25}]_{\text{MAX}} \leq 0.03 \quad (1)$$

$$40 \leq \epsilon_{25} \leq 1000 \quad (2)$$

wherein, ϵ_T represents the relative dielectric constant of the high dielectric filler at a temperature T, the temperature T is from -20 to 80°C, ϵ_{25} represents the relative dielectric constant of the high dielectric filler at a temperature of 25°C, and $[(\epsilon_T - \epsilon_{25}) / \epsilon_{25}]_{\text{MAX}}$ denotes a maximum value of an absolute value of a relative dielectric constant variation $(\epsilon_T - \epsilon_{25}) / \epsilon_{25}$.

17. A high dielectric resin film obtained by casting a composition according to Claim 2 on a base substance and removing a solvent.

18. A method of producing a high dielectric resin film comprising casting the composition according to Claim 2 on a base substance, and removing a solvent.

19. A condenser comprising the high dielectric resin film according to Claim 16 as a dielectric layer.